

**IN THE CLAIMS:**

1. (previously presented) A transport and storage carrier for semiconductor members including wafers which is characterized in that the carrier is molded from a resin composition comprising a synthetic resin having a melting temperature of at least 300°C and a carbon fibril admixed with the resin, the molded carrier being 1 to 5 seconds in average charge decay time for decay of 1,000 V to 5 V, and wherein said carbon fibril is 3.5 to 75 nm in average diameter and 5 to 1000 in aspect ratio.

2. (original) A carrier according to claim 1 wherein the synthetic resin is polyetheretherketone, polyetherimide or polyethersulfone.

3. (canceled)

4. (original) A carrier according to claim 1 wherein 1 to 10 parts by weight of the carbon fibril is used per 100 parts by weight of the synthetic resin.

5. (new) A transport and storage carrier for semiconductor members including wafers which is characterized in that the carrier

is molded from a resin composition consisting essentially of a synthetic resin having a melting temperature of at least 300°C and carbon fibril having an average diameter of 3.5 to 75 nm and an aspect ratio of 5 to 1000 admixed with the resin, the molded carrier being 1 to 5 seconds in average charge decay time for decay of 1,000 V to 5 V.

6. (new) A carrier according to claim 5 wherein the synthetic resin is polyetheretherketone, polyetherimide or polyethersulfone.

7. (new) A carrier according to claim 5, wherein 1 to 10 parts by weight of the carbon fibril is used per 100 parts by weight of the synthetic resin.